UMS Integration Limited
FY2025 AGM Presentation

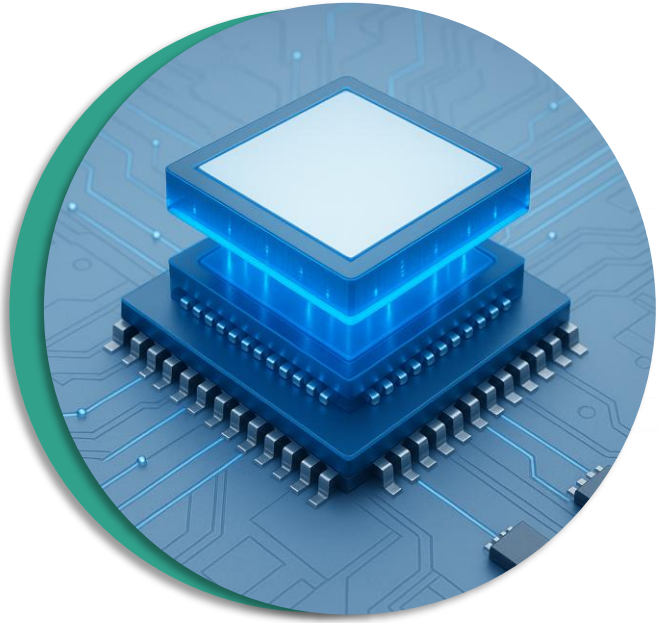
FORWARD LOOKING STATEMENT

This presentation contains forward looking statements which can be identified by the context of the statement and generally arising when the Company is discussing its beliefs, estimates or expectations. Such statements may include comments on industry, business or market trends, projections, forecasts, and plans and objectives of management for future operations and operating and financial performance, as well as any related assumptions.

Readers of this presentation should understand that these statements are not historical facts or guarantees for future performance but instead represent only the Company's belief at the time of the statement were made regarding future events, which are subject to significant risks, uncertainties and other factors, many of which are outside the Company's control. Actual results and outcomes may differ materially from what is expressed or implied in such forward-looking statements.

The Company cautions readers not to place undue reliance on any forward-looking statements included in this presentation, which speaks only as of the date made; and should any of the events anticipated by the forward-looking statements transpire or occur, the Company makes no assurances on what benefits, if any, the Company will deliver there from.

CONTENT



- ❑ Business Overview
- ❑ Financial Performance
- ❑ Industry Outlook & Key Growth Drivers
- ❑ Future Strategies

Business Overview

Your strategic partner for success.

GLOBAL MANUFACTURING LOCATIONS

California, USA

- Procurement and Purchasing Centre
- 7,500 sqft
- Close Proximity to AMAT's R&D Function

Malaysia UMS

- Volume Production
- 1,000,000 sqft

Singapore UMS

- Corporate Headquarter
- 150,000 sqft
- R&D, Engineering and other High-Value Added Activities

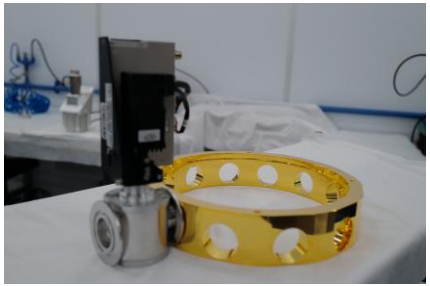
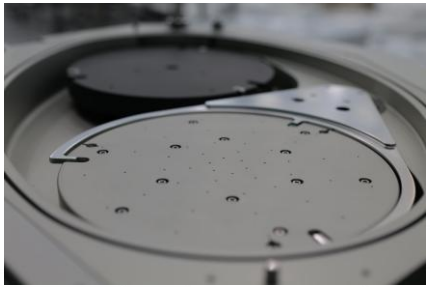
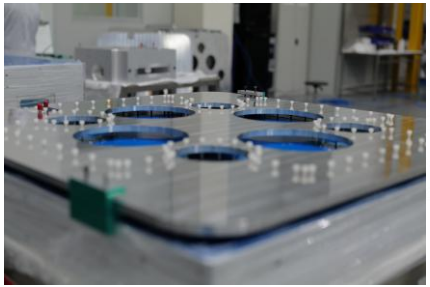
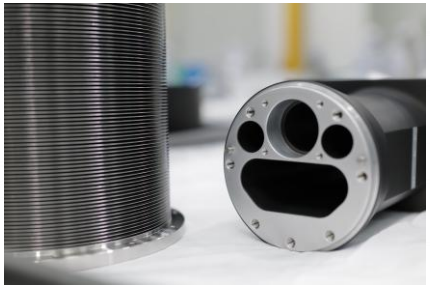
Singapore JEP

JEP Engineering

PENANG PLANT EXPANSION

- P30B construction started in Mar 2026.
- Land acquired in 2025
- 300,000 sq ft, Cleanroom assemblies on L2
- Lights-out manufacturing - fully automated production facilities that operate without human intervention, allowing them to run 24/7 with lights turned off. Utilizing AI, robotics, and IoT, these factories maximize efficiency, reduce labor costs, and optimize energy consumption

SEMICONDUCTOR COMPONENTS

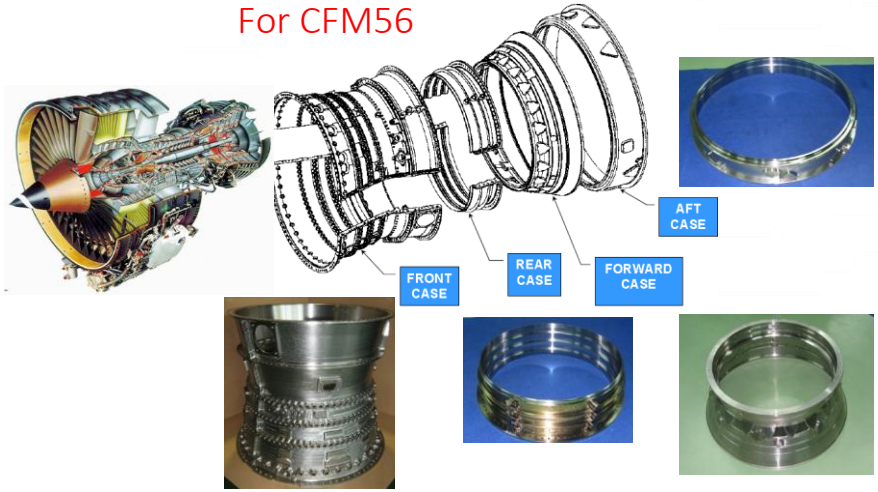
- Semiconductor machined components are high-precision, contaminant-free parts manufactured via CNC milling, turning, and grinding for chip fabrication equipment.
- They require extreme tolerances and specialized materials like stainless steel, aluminum, quartz, and ceramics.
- Surface treatment is required in many components

AEROSPACE COMPONENTS

Products and Programs

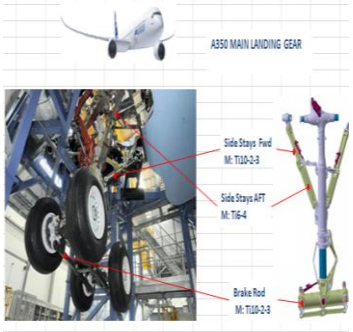
Aero Engine Casing

For CFM56



Landing Gear Products

Brake Rod & Drag Brace



Air Management System

For B787

Financial Performance

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FINANCIAL RESULTS PERFORMANCE
FY2025 VS FY2024

FY 2025 Revenue

$251.1 Million (Up 4%)

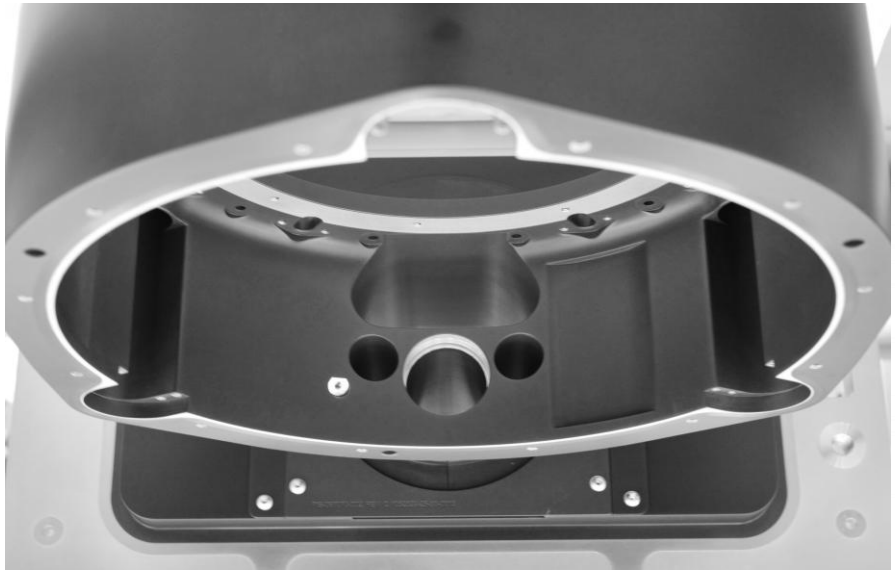
FY 2024 Revenue $242.1 Million

FY 2025 PATMI

$41.6 Million (Up 2%)

FY 2024 PATMI $40.6 Million

FINANCIAL RESULTS PERFORMANCE
4QFY2025 VS 3QFY2025



4QFY2025 2025 Revenue

$66.8 Million (Up 13%)

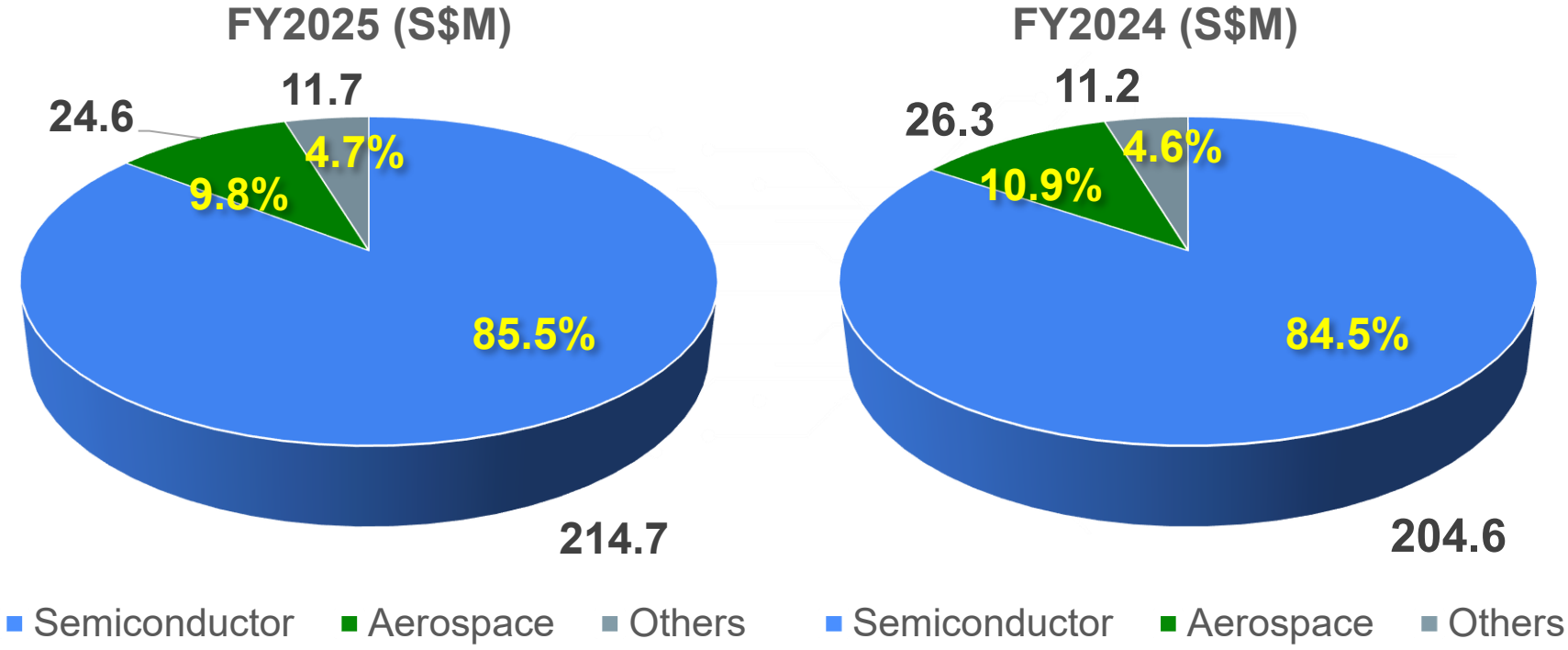
3QFY2025 Revenue $59.3 Million

4QFY2025 PATMI

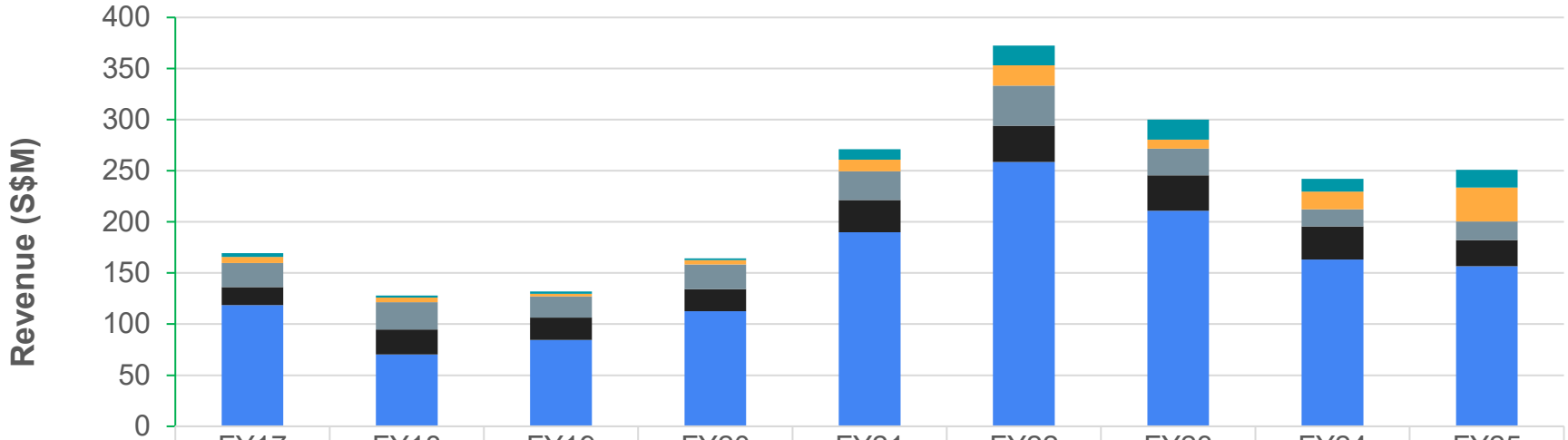
$11.1 Million (Up 6%)

3QFY2025 PATMI $10.5 Million

SEGMENTAL REVENUE CONTRIBUTION FY2025 VS FY2024



GEOGRAPHICAL CONTRIBUTION (FY17-FY25)



	FY17	FY18	FY19	FY20	FY21	FY22	FY23	FY24	FY25
Others	3.7	2	2.3	1.8	10.3	19.3	19.5	12.4	17.4
Malaysia	6	4.5	2.7	4.1	11.5	20	8.9	17.5	33.3
Taiwan	23.6	26.7	20.7	24.2	28	39.2	26	16.5	18.1
United States	17.4	24.5	21.9	21.8	31.5	35.4	34.8	32.6	25.6
Singapore	118.7	70.2	84.4	112.5	189.9	258.6	210.8	163.1	156.6

FY 2025 Key Achievements

- Strengthening relationship with Customer L
- Deepened collaboration with Customer A
  - Integrated System contract renewal
- Installation of production infrastructure and equipment at new Penang factory
- Ramping up NPIs and mass production at new Penang factories
- Completed Secondary listing in Bursa Malaysia
- iEdge Singapore Next 50 Index component stock
- 1 for 4 Bonus share issue
- Market Cap exceeded S$1 billion

Industry Outlook & Key Growth Drivers

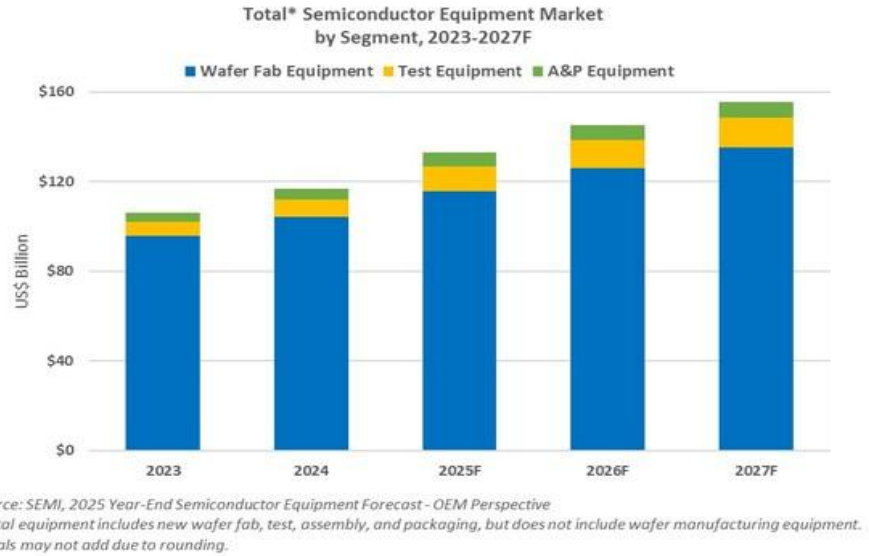
Your strategic partner for success.

SEMICONDUCTOR INDUSTRY OUTLOOK

Global Demand to Surge and Fab Spending To Accelerate

Global sales of total semiconductor manufacturing equipment by original equipment manufacturers (OEMs) are forecast to reach a record high of $145 billion in 2026 and $156 billion in 2027.

This growth will be driven primarily by investments related to AI, particularly in leading-edge logic, memory, and the adoption of advanced packaging technologies.



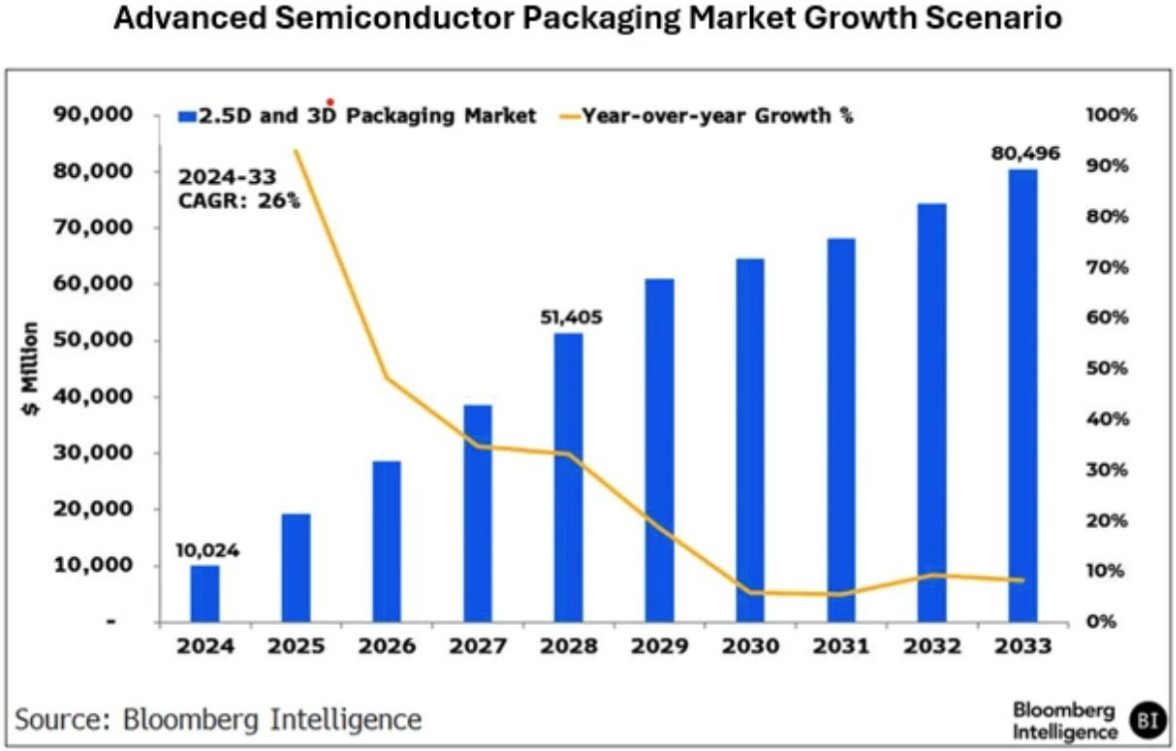
Source: SEMI, 2025 Year-End Semiconductor Equipment Forecast - OEM Perspective
**Total equipment includes new wafer fab, test, assembly, and packaging, but does not include wafer manufacturing equipment. Totals may not add due to rounding.*

[1] Source: https://www.semi.org/en/semi-press-release/global-semiconductor-equipment-sales-projected-to-reach-a-record-of-156-billion-dollars-in-2027-semi-reports

ADVANCED PACKAGING : SURGING GROWTH PROSPECTS

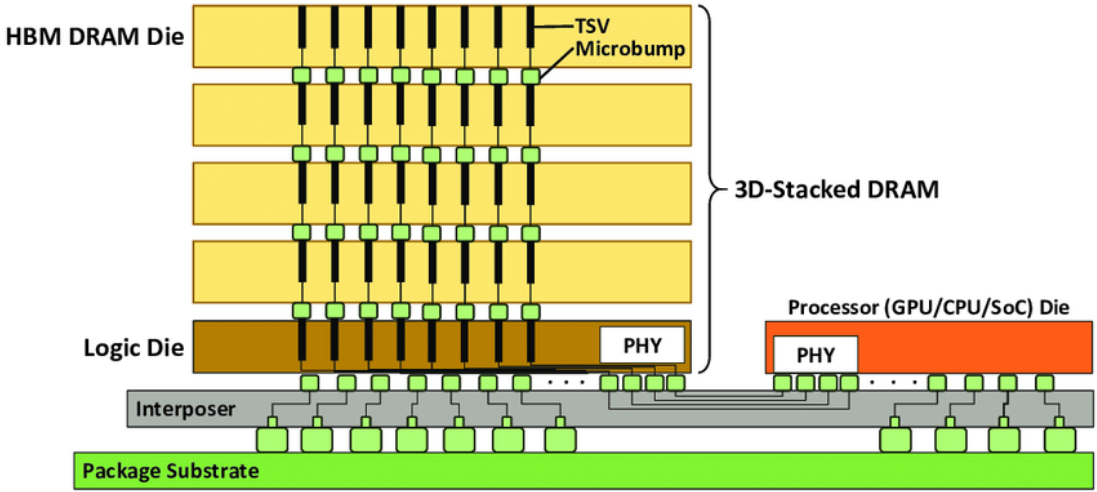
- Bloomberg Intelligence (BI) finds that the market for advanced semiconductor packaging could grow eightfold to $80.5 billion by 2033, driven by the spread of AI chips from data centers into consumer electronics and automotive applications. The 26% compound annual growth rate significantly outpaces the 10% projected growth for the overall semiconductor industry.
- By 2033, BI finds that advanced packaging will reach 90% penetration in PCs, along with all graphics processors and half of smartphone chips. Automotive processors are expected to hit 18% adoption as autonomous driving systems require more computing power in compact, energy-efficient packages
- AI chip package sizes are expected to triple by 2030 as designs incorporate more computing cores and memory stacks.
- Packaging costs for top-end AI chips could climb to nearly $1,300 per chip in 2028 before falling 45% by 2033 as panel-level packaging and mature 3D stacking reset the cost curve.
- Hybrid bonding technology – which creates copper-to-copper connections thousands of times denser than current methods – will become the preferred solution for cloud AI and autonomous driving after 2028.
- Tight capacity is expected to persist through 2027, with broader AI adoption driving the next expansion phase.
- The improvements in chipmaking hardware are outpacing Moore's Law. Therefore, the requirement for advanced packaging technology.
- ***Source: https://www.bloomberg.com/company/press/advanced-semiconductor-packaging-market-could-reach-80-billion-by-2033-as-ai-chips-spread-to-consumer-devices-according-to-bloomberg-intelligence/***

ADVANCED PACKAGING : SURGING GROWTH PROSPECTS



ADVANCED PACKAGING

- **Chiplet-based design** combines multiple chips into one single chip, enabling modular building blocks that extend Moore's Law beyond traditional flat (horizontal) layout
- **GPU and memory chips** are tightly interconnected to optimize high-speed data and power transfer using specialized interconnect technologies tailored to the chip's function



Front-End Processing in Advanced Packaging

U-Bump / RDL Packaging

- Thin-film barrier deposited via PVD
- Photoresist patterning and residue removal (descumming)
- Electroplating to form interconnects
- Photoresist stripping and etching of excess PVD film
- Similar steps are used to fabricate chiplets within the package

Through - Silicon Via (TSV) Packaging

- Wafer patterning and etching to define vertical vias
- Cleaning to remove photoresist and etch residues
- PVD + electroplating to form TSV metal connections
- Polishing to remove excess material
- Wafer bonding, flipping, grinding and etching to expose TSVs
- Final passivation for protection

Our key customers provide tools to support the creation of bumps, pillars, RDL, TSVs, TDVs, TGVs, and hybrid bonding

UMS' ROLE IN THE ADVANCED PACKAGING VALUE CHAIN

Supplier of critical components (chambers) for various tools including:

- Electrofill product family that produce void-free fill for a wide range of TSV sizes, as well as on-wafer performance stability, resulting in a wide range of design possibilities for complex chips
- Electrochemical deposition for superior bump height uniformity and co-planarity control with high plating rates and footprint efficiency. It also delivers perfect wiring inside complex features with zero defects and excellent conductor properties
- Carrier-less backside deposition – for precise wafer shape management that improves bonding yield

Participant of the next gen advanced packaging technology development program:

- Working with key research institution on development of next-generation advanced packaging technology, involving the use of large rectangular panels instead of round wafers for greater efficiency, lower cost, and higher production capacity, especially for AI chips like those from Nvidia, featuring large-area panel-level integration for high-performance computing.
- This "circle to square" transition aims to overcome current format limitations, enabling integration of more chips with better area utilization, with pilot lines starting in 2026 and mass production targeted for 2028-2029.

AEROSPACE INDUSTRY OUTLOOK

SOARING GROWTH PROSPECTS

The aerospace industry remains robust driven by strong air travel demand and increased defence spending, with the global market projected to grow significantly. Key challenges include persistent supply chain constraints, labour shortages and geopolitical issues.

Despite these challenges, the industry is focused on long-term resilience and innovation in areas like sustainable aviation and AI.

According to IATA, the number of air travellers is expected to rise 4.4% to 5.2 billion in 2026 with passenger loads reaching an all-time high. In the Asia-Pacific – the largest market globally – passenger load factors are projected to reach another record of 84.4% despite a slower recovery in international traffic. [1]

[1] *Source: https://www.straitstimes.com/world/5-2b-air-travellers-expected-globally-in-2026-passenger-loads-to-reach-all-time-high-iata*

Future Strategies

Your strategic partner for success.

LEVERAGING WHAT WE DO BEST

Semiconductor

As the semiconductor market evolves, we meet customer needs and drive operational efficiency through technology.

- ❑ Committed to working closely with key Customers.
- ❑ To invest in new machineries to broaden manufacturing service capabilities.
- ❑ To widen our customer base in the semiconductor segment.

Aerospace

To increase our aerospace product portfolio as the industry caters to the rebound in demand for air travel post-pandemic.

- ❑ To deepen engagement with existing customers, with several products currently in the first article stage.
- ❑ Expects increase in orders as more products receive approval and move into mass production.

UMS GROUP

UMS INTEGRATION LIMITED

https://www.umsgroup.com.sg/

Thank You

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